

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-10 (Canceled)

11. (currently amended) A circuit board comprising:

a substrate;

a plurality of screen-printed patterns formed on said substrate by screen printing, each of said screen-printed patterns including at least one of a passive device such as a capacitor element and/or an active device such as an electromechanical conversion element; and

a gap disposed between said plurality of screen-printed patterns, wherein: a said gap between said pattern is not more than 40  $\mu\text{m}$ .

12. (currently amended) The circuit board according to claim 11, wherein:

~~if it is assumed that a~~ said plurality of screen-printed patterns are formed in an aligned manner on said substrate;

~~a difference between an average thickness of a~~ odd-numbered patterns corresponding to a pattern assumed to be formed by an odd-numbered operation and an average thickness of a even-numbered patterns corresponding to a pattern assumed to be formed by an even-numbered operation is not more than 5% of an overall average thickness.

13. (currently amended) The circuit board according to claim 11, wherein:

~~each of said screen printing is~~ screen printed patterns comprises a printing ink material applied on said substrate performed by using by a mask including a positive pattern section and a negative pattern section with a mask material formed on said negative pattern section, ~~for transferring a wherein said~~ printing ink material is transferred to a ~~said~~ substrate via openings of a mesh disposed at said positive pattern section, and wherein: said negative pattern section of said mesh selectively has a mesh opening ratio which is smaller than an opening ratio of said positive pattern section.

14. (currently amended) The circuit board according to claim 13, wherein a plating layer is formed on said mesh of said negative pattern section of said mask, wherein said plating layer has a thickness of 1 to 20  $\mu\text{m}$ , and wherein said printing ink is not applied to said substrate corresponding to positions on said mask where said plating layer is formed.

15. (canceled)

16. (currently amended) The circuit board according to claim 11, wherein said plurality of screen-printed patterns comprises a single screen-printed layer on said substrate is formed by a one time of screen printing application.

17. (new) The circuit board according to claim 11, wherein:  
said plurality of screen-printed patterns are formed in an aligned manner on said substrate; and  
a difference between thicknesses of two adjacent patterns is not more than 5% of an overall average thickness.